Call for Papers

a Session on

Smart Manufacturing

2016 ASME/ISCIE International Symposium on Flexible Automation (ISFA2016)
InterContinental Hotel & Conference Center
August 1-3, 2016, Cleveland, Ohio, USA

Session Technical Focus

Smart manufacturing technology is rapidly shifting and transforming the global manufacturing paradigm and competitive landscape through an integrated, information-rich, and knowledge-based approach. We cordially invite you to submit a paper to share your knowledge and expertise in all areas related to **Smart Manufacturing**. Papers from the industrial sector are particularly encouraged. The session welcomes both theoretical and applied papers in areas including, but not limited to:

- Smart manufacturing systems, equipment and technologies
- System integration for manufacturing integration
- Crowdsourcing design for manufacturing
- Manufacturing process simulation and optimization
- Information technology
- Smart and intelligent manufacturing processes
- Cloud-enabled manufacturing systems and applications
- Industrial Internet for of Things
- Next-generation robotics and automation
- Measurement and monitoring of smart manufacturing systems

Paper Submission

The deadline for submission of your contribution to this session is **February 29, 2016**. Both short and long papers will be considered and reviewed. For short papers, please submit a summary of 1,000 words or less (short papers will be limited to 4 pages) and, for long papers, please submit a manuscript of no more than eight pages. All summaries and manuscripts should be submitted through the conference website at http://engineering.case.edu/conference/ISFA2016/.

Session Organizers

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